

1752-2 1.1

Material Composition Declaration

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ICP Web Site for information on IPC-1752 Standard
<http://www.ipc.org/IPC-175x>

Form Type*
Distribute

This document is a declaration of the substances within the manufacturer listed item. Note:

if the item is an assembly with lower level parts, the declaration encompasses all lower

level materials for which the manufacturer has engineering responsibility.

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg
Information

Supplier Information

Company Name *	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	Response Date* Sat, Aug 31, 2013 03:59 AM
Contact Name *	Title - Contact Product Ecology	Phone - Contact * 801-562-7455	Email - Contact * david.lancaster@fairchildsemi.com
Authorized Representative *	Title - Representative Product Ecology	Phone - Representative * 801-562-7455	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
P6KE30A	P6KE30A	DO-15			SUBCONTRACTOR	0.387787	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Matte Tin (Sn)	Other	Not Applicable	C	seconds	Not Applicable

* Required Field

RoHS Material Composition Declaration		Declaration Type * Custom
RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium	
<p>This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.</p> <p>The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.</p> <p>Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the minuscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.</p>		
RoHS Declaration *	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions	Supplier Acceptance * Accepted
<p>Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.</p> <p>Exemption List Version EL-2011/534/EU 7(a)-Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead).</p>		

Declaration Signature

Supplier Signature	
DAVID LANCASTER - PRODUCT ECOLOGY MANAGER	

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name DO-15

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
CSS Wire	Other Ferrous alloys, non-stainless steels	202.316	Supplier		Carbon	1.010	7440-44-0	2605
			Supplier		Copper	70.700	7440-50-8	182317
			Supplier		Iron	130.000	7439-89-6	335236
			Supplier		Manganese	0.404	7439-96-5	1042
			Supplier		Phosphorus	0.101	7723-14-0	260
			Supplier		Sulfur	0.101	7704-34-9	260
			Supplier		Silicon	0.093	7440-21-3	239
Chip	Other inorganic materials	0.093	Supplier		Lead	0.104	7439-92-1	268
Die Attach	Other Nonferrous metals & alloys	0.112	A	Lead/Lead Compounds	Silver	0.003	7440-22-4	7
					Tin	0.006	7440-31-5	14
					Cobalt	0.505	7440-48-4	1302
Dumet Wire	Other Ferrous alloys, non-stainless steels	101.016	Supplier		Iron	57.000	7439-89-6	146988
			Supplier		Manganese	0.808	7439-96-5	2084
			B	Nickel (external applications only)	Nickel	42.400	7440-02-0	109338
			Supplier		Silicon	0.303	7440-21-3	781
					Antimony Trioxide	1.620	1309-64-4	4178
Encapsulation	Thermoplastics	77.200	B	Antimony/Antimony Compounds	Bromine Resin	1.390	6386-73-8	3584
					Carbon Black	0.772	1333-86-4	1991
				Brominated Flame Retardants (other than PBCs or PBDEs)	Epoxy Resin	19.300	29690-82-2	49770
					Silica, vitreous	54.128	60676-86-0	139582
Plating	Other Nonferrous metals & alloys	7.040	Supplier		Tin	7.040	7440-31-5	18154